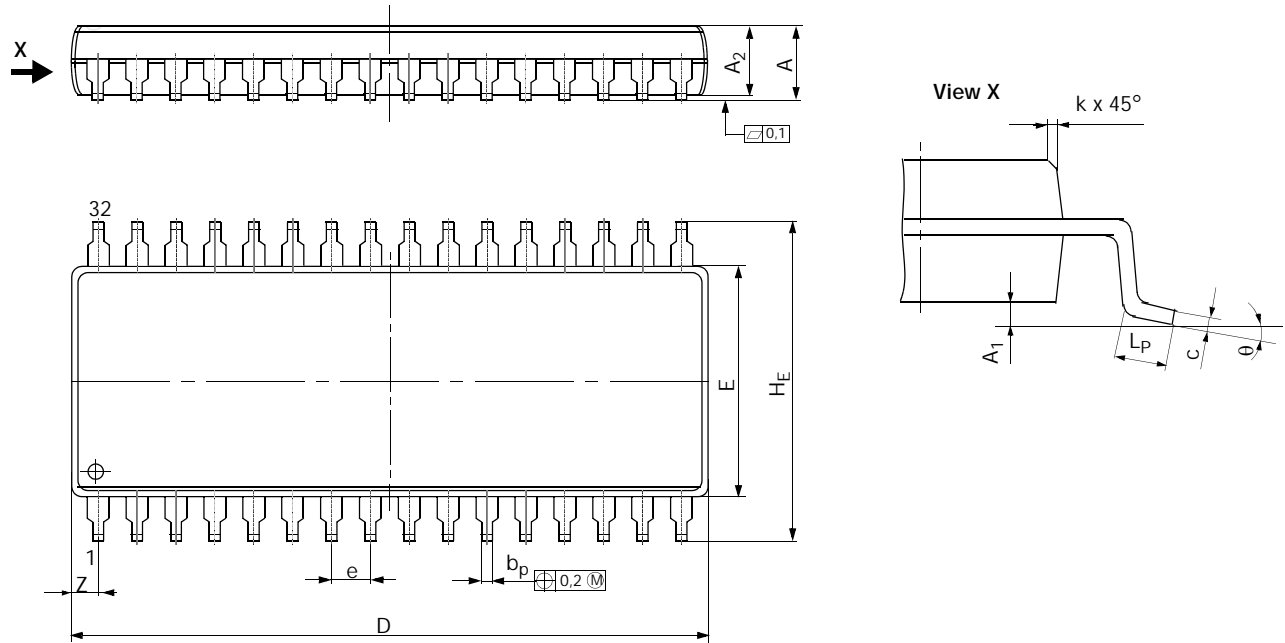
	Package SOP32 (300 mil)	MDS 745
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Dimensions in millimetres

Based on JEDEC: JEP95 MO-119

1 Dimensions

Dimensions of Sub-Group B1	
A_{max}	2,54
b_{Pmin}	0,36
b_{Pmax}	0,51
e_{nom}	1,27
H_{Emin}	10,29
H_{Emax}	10,64
L_{Pmin}	0,53
Z_{max}	0,91

Dimensions of Sub-Group C1	
A_{min}	2,29
A_{1min}	0,102
A_{1max}	0,254
A_{2min}	2,18
A_{2max}	2,29
c_{min}	0,15
c_{max}	0,32
D_{min}^*	20,57
D_{max}^*	20,88
E_{min}^*	7,42
E_{max}^*	7,60
k_{min}	0,25
θ_{min}	0°
θ_{max}	8°

- | | |
|--------------------------------|------------------------|
| 2 Weight | $\leq 0,91$ g |
| 3 Package Body Material | Low Stress Epoxy |
| 4 Lead Material | FeNi-Alloy or Cu-Alloy |
| 5 Lead Finish | solder plating |
| 6 Lead Form | Z-bends |

* without mold-flash

Zentrum Mikroelektronik Dresden		
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